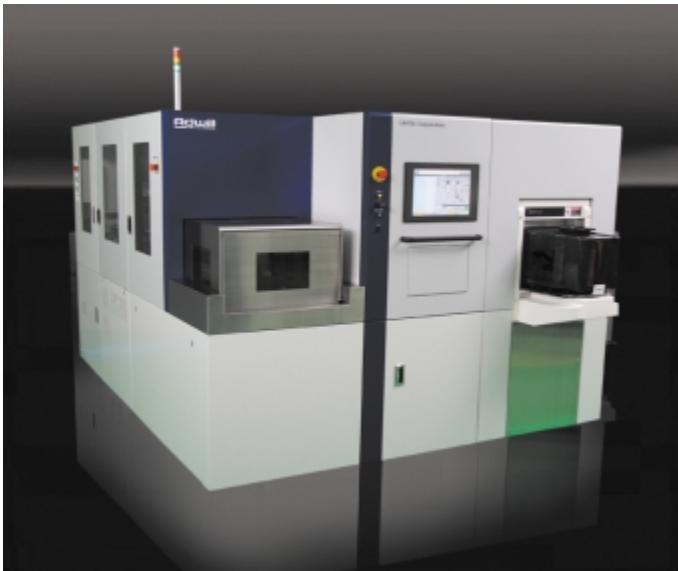


Fully-Automatic Vacuum Mounter

RAD-2512F/12



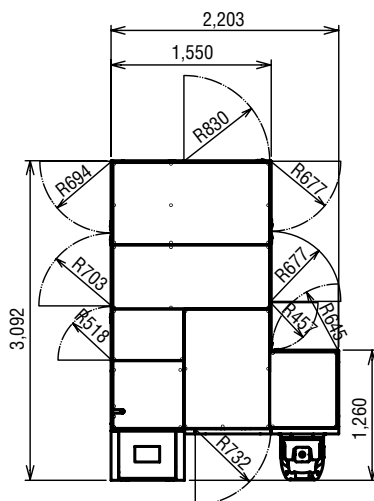
Outline

- Fully-automatic wafer mounter equipped with a pre-cut tape mounting function in a vacuum environment.
- By using our unique vacuum control method, wafer mounting is performed without any contact with wafer surface.
- By adopting the non-contact wafer backside handling method, contamination of wafer is prevented.

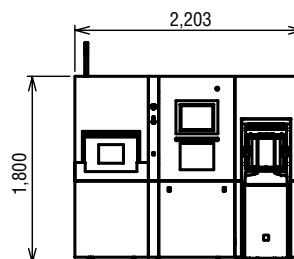
- Options**
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
 - Vision System (Wafer ID Reader & Barcode Attachment System)
 - Dicing Tape In-line Pre-cutting
 - RFID Traceability System

- Suitable Tape**
- Dicing tape: Adwill D series, G series

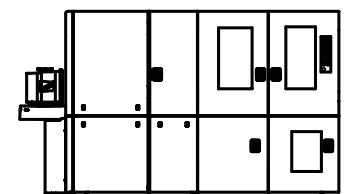
External View



Top View



Front View



Right Side View

Unit:mm

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 4.0kW
Air Supply	Air pressure	: 0.6-0.8MPa
	Air consumption	: >800L/min (ANR)
Vacuum Supply (for workpiece) (for vacuum chamber)	Vacuum pressure	: >-80kPa
	Ultimate Pressure	: 1.0Pa
	Pumping Speed	: >250L/min

Applicable Wafer Size 200mm (*300mm currently in development)

Size

Width : 2,203mm
Depth : 3,092mm
Height : 1,800mm
(excluding the signal tower and protruding parts)

Weight 2,600kg

UPH 20wafers/hour

The above processing capacity is based on following conditions:

Wafer	: 200mm diameter non-polished mirror wafer
Ring frame	: for 200mm wafer
Dicing tape	: D-184 from LINTEC



LINTEC Corporation *Linking your dreams*

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